



Application of Hyperspectral Imaging for Nondestructive Measurement II

Guest Editor:

Prof. Dr. Byoung-Kwan Cho

Nondestructive Bio-Sensing
Laboratory, Department of
Biosystems Machinery
Engineering, Chungnam National
University, Daejeon, 34134, Korea

Deadline for manuscript
submissions:

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Message from the Guest Editor

Dear Colleagues,

Hyperspectral imaging (HSI) technology has recently emerged as a powerful analytical technique, using vibrational spectroscopy for nondestructive quality measurement of various materials. The sample analysis is also more convenient and comparatively fast with the hyperspectral imaging technique, due to a large number of samples being analyzed at the same time rather than the single sampling technique used by the other spectroscopic methods.

This Special Issue, the second on this topic, focuses on the latest research and developments of hyperspectral imaging in nondestructive measurement applications. Accordingly, papers that demonstrate novel hyperspectral imaging technology concepts for nondestructive measurement are sought. These include papers dealing with theoretical analyses and laboratory and field studies in various industries, such as agriculture, food, pharmaceutical, natural science, etc.

We would like to invite you to submit original research papers for the “Application of Hyperspectral Imaging for Nondestructive Measurement II” Special Issue.

Prof. Dr. Byoung-Kwan Cho

Guest Editor





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Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo
Dipartimento di Fisica,
Politecnico di Milano, Piazza L.
da Vinci 32, 20133 Milano, Italy

Message from the Editor-in-Chief

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Applied Sciences Editorial Office
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